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In the Claims

Please amend Claim 1 as follows.

- 1 1. **(Currently Amended)** An integrated circuit chip
2 board, the chip board comprising:
3 a ~~plurality~~ multiplicity of ~~components~~ semiconductor
4 chips for processing signal groups, wherein a plurality of
5 semiconductor chips exchange signal groups using wireless
6 techniques, the multiplicity of semiconductor chips
7 including; and
8 ~~a group of components for at least one selected~~
9 semiconductor chip receiving wireless signal groups from at
10 least one predetermined semiconductor chip on the circuit
11 board, the group of components including; selected
12 semiconductor chips having:
13 an antenna for receiving ~~radio-frequency~~ wireless
14 signals;
15 a ~~radio-frequency~~ wireless signal receiver
16 coupled to the antenna, the receiver detecting the ~~radio~~
17 frequency wireless signals; and
18 a demodulator coupled to the receiver, the
19 demodulator recovering signal groups in the ~~radio-frequency~~
20 wireless signals, ~~the signal groups being applied to the~~
21 plurality of components.
22
23 2. **(Withdrawn; Non-Elected)**
24

1 Please amend Claim 3 as follows.

2

3 3. **(Currently Amended)** The ~~chip~~ integrated circuit
4 board as recited in claim 1 wherein signals received by the
5 ~~radio-frequency~~ the selected semiconductor chip receiver
6 are modulated with a modulation from the group consisting
7 of amplitude modulation and frequency modulation.

8

9 Please amend Claim 4 as follows.

10

11 4. **(Currently Amended)** The ~~chip~~ integrated circuit
12 board as recited in claim 1 wherein the selected
13 semiconductor chip further ~~including~~ includes an analyzer,
14 the analyzer receiving ~~signals~~ signal groups from the
15 demodulator, the analyzer ~~decodes~~ decoding the signal from
16 the demodulator into a plurality of logic signals.

17

18 5. **(Withdrawn; Non-Elected Claim)**

19

20 6. **(Withdrawn; Non-Elected Claim)**

21

22 7. **(Withdrawn; Non-Elected Claim)**

23

24

25 Please amend Claim 8 as follows.

26

27 8. **(Currently Amended)** The ~~chip~~ integrated circuit
28 board as recited in claim 1 wherein the signal groups
29 include a header portion, a data portion, and a tail
30 portion.

1 Please amend Claim 9 as follows.

2

3 9. **(Currently Amended)** A method for transferring
4 logic signal groups between ~~integrated circuit~~ semiconductor
5 chips, the method comprising:

6 modulating and transmitting a ~~radio-frequency~~ wireless
7 signal by a first ~~integrated circuit~~ semiconductor chip,
8 the wireless signal being modulated with logic signal
9 groups generated by the first ~~integrated circuit~~
10 semiconductor chip; and

11 receiving and demodulating the ~~radio-frequency~~
12 wireless signal by a second ~~integrated circuit~~
13 semiconductor chip.

14

15 Please amend Claim 10 as follows.

16

17 10. **(Currently Amended)** The method as recited in
18 claim 9 wherein the ~~radio-frequency~~ wireless signal
19 transmits signal groups formatted in a serial format.

20

21 11. **(Withdrawn; Non-Elected Claim)**

22

23 Please amend Claim 12 as follows.

24

25 12. **(Currently Amended)** The method as recited in
26 claim 9 wherein the ~~modulation of the carrier frequency~~
27 wireless signal transmitting the signal groups is
28 ~~modulation~~ modulated with a modulation selected from the
29 group consisting ~~of~~ of amplitude modulation and frequency
30 modulation.

1 Please amend Claim 13 as follows.

2

3 13. **(Currently Amended)** The method as recited in
4 claim 9 wherein a ~~transmitted~~ wireless signal is encoded
5 ~~with a signal identifying to identify a~~ preselected pattern
6 of signals.

7

8 Please amend Claim 14 as follows.

9

10 14. **(Currently Amended)** The method as recited in
11 claim 13 wherein the receiving and demodulating of the
12 wireless signal provide a decoded signal representing a
13 preselected pattern of logic signals.

14

15 Please amend Claim 15 as follows.

16

17 15. **(Currently Amended)** A system for transferring
18 data signal groups between ~~integrated circuit~~ semiconductor
19 chips: the system comprising:

20 ~~a first integrated circuit chip, the first integrated~~
21 ~~circuit~~ at least one transmitting semiconductor chip
22 including:

23 a first processing unit; and

24 a ~~radio~~ wireless transmitting unit coupled to the
25 first processing unit and receiving signal groups there
26 from, the ~~radio~~ wireless transmitting unit transmitting the
27 signal groups from the first processing unit; and

28 ~~a second integrated circuit, the second integrated~~
29 ~~circuit~~ at least one receiving semiconductor chip
30 including:

1 a second processing unit, and
2 a ~~radio~~ wireless receiving unit coupled to the
3 second processing unit, the ~~radio~~ wireless receiving unit
4 receiving ~~radio~~ the signal groups from the transmitting
5 unit, the ~~transmitting unit~~ receiving unit applying the
6 signal groups to the second processing unit.

7
8 16. **(Withdrawn; Non-Elected Claim)**

9
10 17. **(Withdrawn; Non-Elected)**

11
12 18. **(Original)** The system as recited in claim 15
13 wherein the transmitting ~~unit~~ semiconductor chip includes a
14 synthesizer and the receiving ~~unit~~ semiconductor chip
15 includes an analyzer for processing ~~serial~~ serially
16 transmitted ~~information~~ signal groups.

17
18 Please amend Claim 19 as follows.

19
20 19. **(Currently Amended)** The system as recited in
21 claim 15 wherein the ~~first integrated circuit~~ transmitting
22 semiconductor chip is located on a first circuit board and
23 the ~~second integrated circuit~~ receiving semiconductor chip
24 is located on a second circuit board, the first circuit
25 board and the second circuit board being in a stacked
26 configuration.

1 20. **(Original)** The system as recited in claim 15
2 wherein the signal groups include a header portion, a data
3 portion and a tail portion.
4

5 Please add Claim 21.
6

7 21. **(New)** The integrated circuit board as recited
8 in claim 1 wherein the integrated circuit board is a
9 semiconductor substrate, the semiconductor chips being
10 fabricated on the semiconductor substrate.
11

12 Please add Claim 22.
13

14 22. **(New)** The method as recite in claim 9 wherein
15 the semiconductor chips are positioned on an integrated
16 circuit board.
17

18 Please add Claim 23.
19

20 23. **(New)** The system as recited in claim 15
21 wherein the transmitting semiconductor chip and the
22 receiving semiconductor chip are fabricated on the same
23 substrate.